

## **SPECIFICATION FOR LCD MODULE**

**MODULE NO: AFY240320B0-2.8N6NTM REVISION NO: V01** 

Customer's Approval:							
	OLOMATURE	DATE					
	SIGNATURE	DATE					
PREPARED BY (RD ENGINEER)							
CHECKED BY							
APPROVED BY							

## **Records of Revision**

DATE	REF.PAGE PARAGRAPH DRAWING No.	REVISED No.	SUMMARY	REMARK
2017-04-01		V01	First Issue	

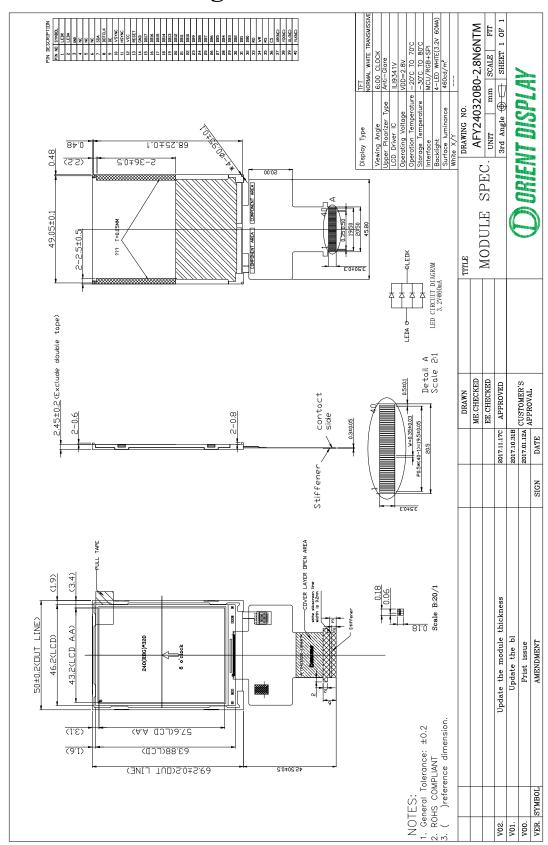
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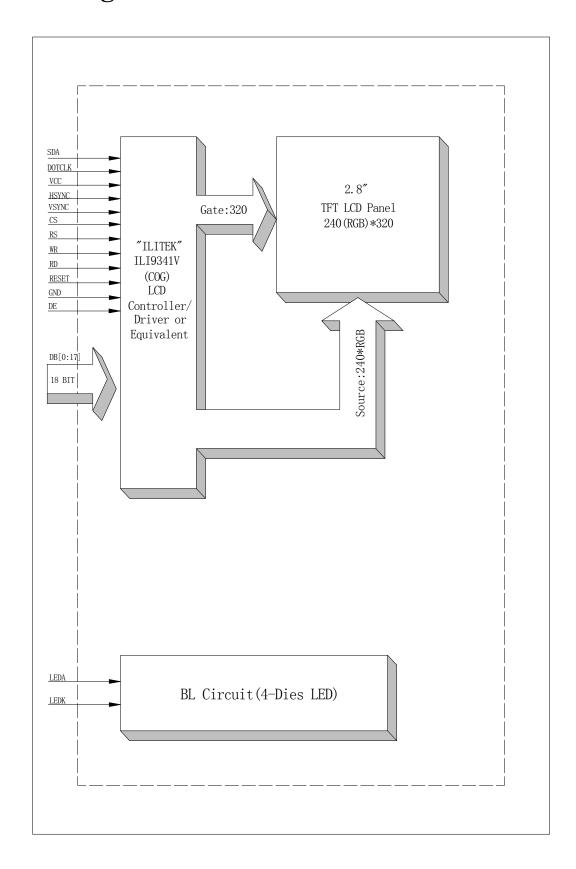
# 1. General Specification

Item	Contents	Unit
LCD TYPE	TFT/TRANSMISSIVE	
MODULE SIZE (W*H*T)	50.00*69.20*2.45	MM
ACTIVE SIZE (W*H)	43.20*57.60	MM
PIXEL PITCH (W*H)	0.180*0.180	MM
NUMBER OF DOTS	240*320	
DRIVER IC	ILI9341V	
INTERFACE TYPE	MCU/RGB+SPI	
TOP POLARIZER TYPE	ANTI-GLARE	
RECOMMEND VIEWING DIRECTION	6	O'CLOCK
GRAY SCALE INVERSION DIRECTION	12	O'CLOCK
BACKLIGHT TYPE	4-DIES WHITE LED	
TOUCH PANEL TYPE	WITHOUT	

# 2. Mechanical Drawing



# 3. Block Diagram



## 4. Interface Pin Function

Pin No.	Symbol	Description	Remark
1	LEDK	Cathode of LED backlight	
2	LEDA	Anode of LED backlight	
3	GND	Power ground	
4	NC	No connect	
5	NC	No connect	
6	NC	No connect	
7	SDA	Data input pin in serial interface	
8	DOTCLK	Dot-clock signal and oscillator source.	
9	DE	Line Synchronization input	
10	VSYNC	Frame/Ram Write Synchronization input	
11	HSYNC	Line Synchronization input	
12	VCC	Power supply	
13	RESET	Reset pin	
14	GND	Power ground	
15~32	DB17~DB00	Data bus	
33	RD	Read data signal	
34	WR	Write data signal	
35	RS	Data or command select	
36	CS	Chip select input pin ("Low" enable).	
37	XR/NC	No connect	
38	YD/NC	No connect	
39	XL/NC	No connect	
40	YU/NC	No connect	

# **5. Absolute Maximum Ratings**

Parameter	Symbol	Min	Max	Unit
Supply voltage for analog	VCC	-0.3	4.6	V
Supply voltage for logic	VCC	-0.3	4.6	V
Supply current (One LED)	I <sub>LED</sub>		30	mA
Operating temperature	$T_{OP}$	-20	+70	°C
Storage temperature	T <sub>ST</sub>	-30	+80	°C

Note: The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

## 6. Electrical Characteristics

## **6.1 Input Power**

Item	Symbol	Min	Typ.	Max	Unit	Applicable terminal
Supply Voltage for Analog	VCC	2.5	2.8	3.3	V	
Supply Voltage for Logic	VCC	1.65	1.8/2.8	3.3	V	
Input Voltage	$V_{\mathrm{IL}}$	GND	-	0.3VCC	V	
input voltage	$ m V_{IH}$	0.8 VCC	-	VCC	, v	
Input leakage Current	$I_{LKG}$	-1		1	μА	

## **6.2 Backlight Driving Conditions**

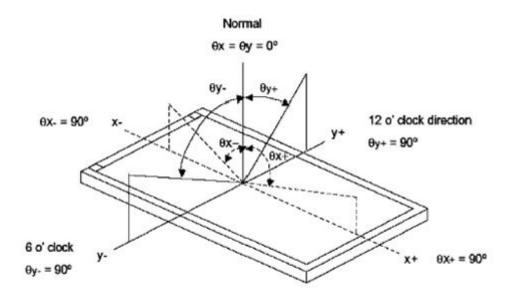
Idom	Crush al		Value	Unit	Remar		
Item	Symbol	Min.	Тур.	Max.	Unit	k	
Voltage for LED Backlight	V <sub>F</sub>	2.8	3.2	3.4	V	I <sub>L</sub> =60mA	
Current for LED Backlight	IL		60	-	mA		
Power Consumption	P		0.192		W		
LED Life Time		30,000	50,000		Hr	Note	

**Note**: Brightness to be decreased to 50% of the initial value at ambient temperature TA=25 $^{\circ}$ C

# 7. Optical Characteristics

ITEN	. Л	CVMDOI	CONDITIONS	SPECIFICATIONS			HINIT	NOTE
ITEM		SYMBOL	CONDITIONS	MIN	TYP.	MAX	UNIT	NOTE
Lumina	nce	L	I <sub>L</sub> =60mA	360	460	560	Cd/m <sup>2</sup>	
Contrast 1	Ratio	CR	θ=0°	400	500			
Dagnanga	Time	Ton	25℃		25	30		
Response	Time	Toff	23 C		25	30	ms	
	Red	XR						
	Red	YR						
	Green	XG	Viewing normal					
CIE Color		YG						
Coordinate	Blue	Хв	angle					
		Yв						
	White	Xw		0.290	0.310	0.330		
	winte	Yw		0.340	0.360	0.380		
	Hor.	$\theta_{X+}$		60	70			
Viewing	1101.	$oldsymbol{ heta}_{X-}$	CR≥10	60	70		Degree	
Angle	Ver.	$oldsymbol{ heta_{Y+}}$	CK=10	60	70		Degree	
	v C1.	$ heta_{\scriptscriptstyle Y-}$		50	60			
Uniformity	Un			80			%	

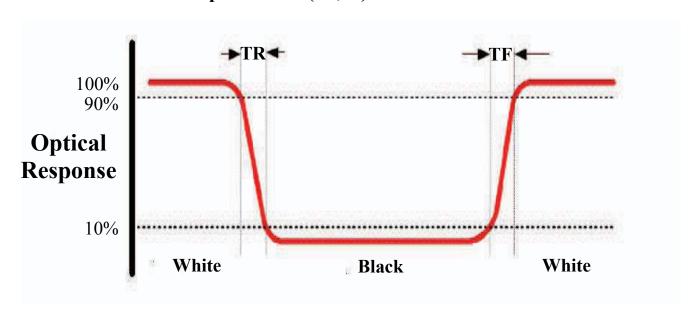
Note 1: Definition of Viewing Angle  $\theta x$  and  $\theta y$ :



Note 2: Definition of contrast ratio CR:

$$CR = \frac{Luminance of white state}{Luminance of black state}$$

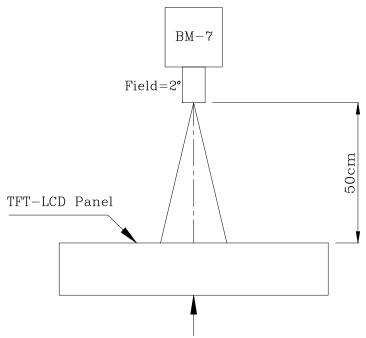
Note 3: Definition of Response Time(Tr,Tf)



#### **Note 4: Definition of Luminance**

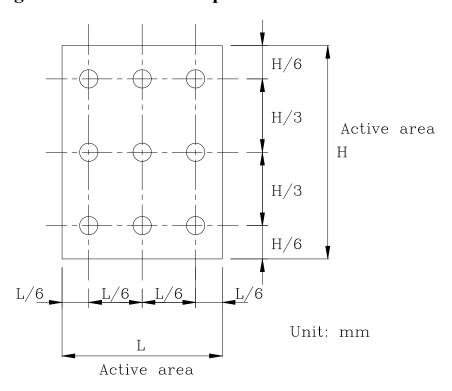
### **1** The Brightness Test Equipment Setup

Field=2° (As measuring "black" image, field=2° is the best testing condition)



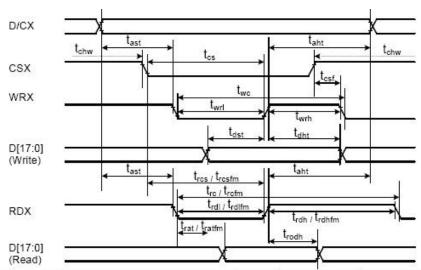
The center of the screen

## **2** The Brightness Test Point Setup



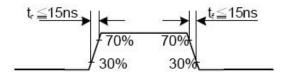
# 8. Timing Characteristics

#### 8.1 MPU interface characteristic

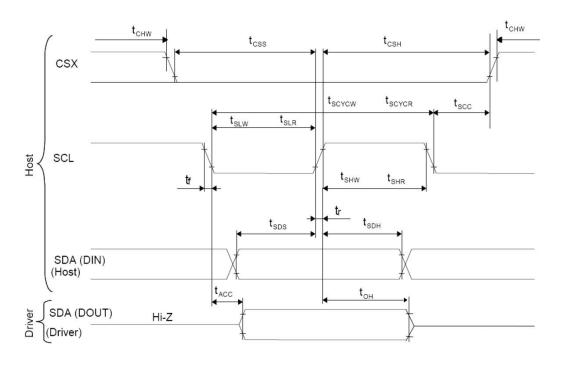


Signal	Symbo	Parameter	min	max	Unit	Description
Day	tast	Address setup time	0	- 170	ns	
DCX	taht	Address hold time (Write/Read)	0		ns	
× ×	tchw	CSX "H" pulse width	0	-	ns	
	tcs	Chip Select setup time (Write)	15		ns	
CSX	trcs	Chip Select setup time (Read ID)	45	-	ns	
Î	trcsfm	Chip Select setup time (Read FM)	355	141	ns	
	tcsf	Chip Select Wait time (Write/Read)	10	- 2	ns	
į.	twc	Write cycle	66	357	ns	
WRX	twrh	Write Control pulse H duration	15	- 17.	ns	
	twrl	Write Control pulse L duration	15		ns	
×	trcfm	Read Cycle (FM)	450	-	ns	
RDX (FM)	trdhfm	Read Control H duration (FM)	90		ns	
92 30 0	trdlfm	Read Control L duration (FM)	355	-	ns	
	trc	Read cycle (ID)	160	141	ns	
RDX (ID)	trdh	Read Control pulse H duration	90	2	ns	
1-04040500000000000000000000000000000000	trdl	Read Control pulse L duration	45	857	ns	
D147.01	tdst	Write data setup time	10	977	ns	
D[17:0],	tdht	Write data hold time	10		ns	For maximum 01 -30-5
D[17:10]&D[8:1],	trat	Read access time		40	ns	For maximum CL=30pF
D[17:10], D[17:9]	tratfm	Read access time	1	340	ns	For minimum CL=8pF
	trod	Read output disable time	20	80	ns	

Note: Ta = -30 to 70 °C, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, VSS=0V.

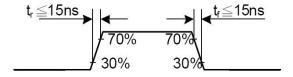


## 8.2 Serial interface timing characteristic(3-line SPI system)

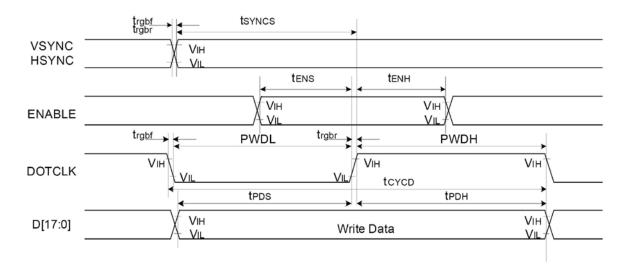


Signal	Symbol	Parameter	min	max	Unit	Description
	tscycw	Serial Clock Cycle (Write)	100	-	ns	_
	tshw	SCL "H" Pulse Width (Write)	40	-	ns	
SCL	tslw	SCL "L" Pulse Width (Write)	40	-	ns	
SCL	tscycr	Serial Clock Cycle (Read)	150	120	ns	
	tshr	SCL "H" Pulse Width (Read)	60	A-54	ns	
	tslr	SCL "L" Pulse Width (Read)	60	_	ns	
SDA / SDI	tsds	Data setup time (Write)	30	-	ns	
(Input)	tsdh	Data hold time (Write)	30		ns	
SDA / SDO	tacc	Access time (Read)	10	-	ns	
(Output)	toh	Output disable time (Read)	10	50	ns	
	tscc	SCL-CSX	20	-	ns	
CCV	tchw	CSX "H" Pulse Width	40	120	ns	
CSX	tcss	CCV CCI Time	60	. <del></del> )	ns	
	tcsh	CSX-SCL Time	65	-	ns	

Note: Ta = 25 °C, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, AGND=VSS=0V

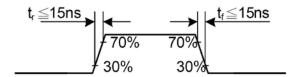


## 8.3 Parallel RGB interface timing characteristic



Signal	Symbol	Parameter	min	max	Unit	Description
VSYNC /	tsyncs	VSYNC/HSYNC setup time	15	í	ns	
HSYNC	t <sub>SYNCH</sub>	VSYNC/HSYNC hold time	15	ī	ns	
DE	t <sub>ENS</sub>	DE setup time	15	ī	ns	
DE	t <sub>ENH</sub>	DE hold time	15	-	ns	
D(17:01	t <sub>POS</sub>	Data setup time	15	-	ns	18/16-bit bus RGB
D[17:0]	t <sub>PDH</sub>	Data hold time	15	-	ns	interface mode
	PWDH	DOTCLK high-level period	15	-	ns	
DOTCLK	PWDL	DOTCLK low-level period	15	-	ns	
DOTCLK	t <sub>CYCD</sub>	DOTCLK cycle time	100	-	ns	
	t <sub>rgbr</sub> , t <sub>rgbf</sub>	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	
VSYNC /	tsyncs	VSYNC/HSYNC setup time	15	-	ns	
HSYNC	tsynch	VSYNC/HSYNC hold time	15	-	ns	
DE	t <sub>ENS</sub>	DE setup time	15	-	ns	
DE	t <sub>ENH</sub>	DE hold time	15	-	ns	
D(47:01	t <sub>POS</sub>	Data setup time	15	-	ns	6-bit bus RGB
D[17:0]	t <sub>PDH</sub>	Data hold time	15	-	ns	interface mode
	PWDH	DOTCLK high-level pulse period	15	-	ns	
DOTCLK	PWDL	DOTCLK low-level pulse period	15	-	ns	
DOTCLK	tcycd	DOTCLK cycle time	50	-	ns	
	t <sub>rgbr</sub> , t <sub>rgbf</sub>	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	

Note: Ta = -30 to 70 °C, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, AGND=VSS=0V



## 9. Standard Specification for Reliability

9.1 Standard Specification for Reliability of LCD Module

No.	Item	Description	Remarks
110.	Ittili		- Temarks
01	High temperature operation	The sample should be allowed to stand at 70°C for 240 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.	Note 1 IEC60068-2-2, GB2423.2-89
02	Low temperature operation	The sample should be allowed to stand at -20°C for 240 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.	Note2 IEC60068-2-1 GB2423.1-89
03	High temperature storage	The sample should be allowed to stand at 80°C for 240 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.	IEC60068-2-2 GB2423.2-89
04	Low temperature storage	The sample should be allowed to stand at -30°C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.	IEC60068-2-1 GB/T2423.1-89
05	Moisture storage	The sample should be allowed to stand at $60^{\circ}\text{C},90\%\text{RH}$ MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.	IEC60068-2-1 GB/T2423.3-2006
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles: -20°C for 30 minutes → normal temperature for 5 minutes → +60°C for 30 minutes → normal temperature for 5 minutes, as one cycle.	Start with cold temperature,end with high temperature IEC60068-2-14, GB2423.22-87
07	Packing vibration	Frequency range: 10Hz ~ 55Hz Amplitude of vibration: 1.5mm Sweep time: 12 min X,Y,Z 2 hours for each direction.	IEC61000-2-6 GB/T2423.5-1995
08	Packing drop test	According to ASTM-D-5327.	IEC60068-2-32 GB/T2423.8-1995
09	Electrical Static	Air: ±4KV 150pF/330Ω 5 times	IEC61000-4-2
09	Discharge	Contact: ±2KV 150pF/330Ω 5 times	GB/T17626.2-1998

Note:1.Ts is the temperature of panel's surface.

<sup>2.</sup> Ta is the ambient temperature of sample.

<sup>3.</sup> Sample size for each test item is 3~5pcs.

## 9.2 Testing Conditions and Inspection Criteria

For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in Table 9.2, standard specifications for reliability will be executed in order to ensure stability.

No.	Item	Test Model	In section Criteria	
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.	
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.	
03	Appearance	Visual inspection	Defect free.	

#### **9.3 MTBF**

Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature (25±5°C), normal humidity (50±10% RH), and in area not exposed to direct sun light.
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## 10. Specification of Quality Assurance

This standard of Quality Assurance confirms to the quality of LCD module products supplied by ODNA.

### 10.1 Quality Test

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

- Electrical-Optical Characteristics: According to the individual specification to test the product.
- Appearance Characteristics: According to the individual specification to test the product.
- Reliability Characteristics: According to the definition of reliability on the specification for testing products.

### 10.2 Delivery Test

Before delivering, the supplier should conduct the delivery test.

- Test method: According to MIL-STD105E.General Inspection Level II take a single Time.
- The defects classify of AQL as following:

Major defect: AQL = 0.65 Minor defect: AQL = 2.5 Total defects: AQL = 2.5

### 10.3 Non-conforming Analysis & Deal With Manners

#### 10.3.1 Non-conforming Analysis

- Purchaser should provide the data detail of non-conforming sample and the non-conforming.
- After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.
- If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.

#### 10.3.2 Disposition of non-conforming

- If any product defect be found during assembling, supplier must change the good for every defect after confirmation.
- Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

## 10.4 Agreement items

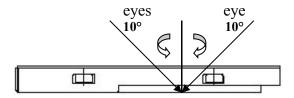
Both parties should negotiate together when the following problems happen.

- There is any problem of standard of quality assurance, and both sides should agree that it must be modified.
- There is any argument item which does not record in the standard of quality assurance.
- Any other special problem.

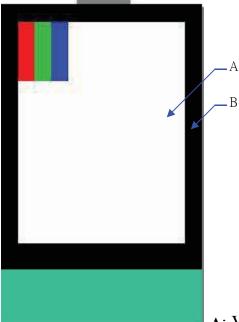
#### 10.5 Standard of The Product Appearance Test

#### 10.5.1 Manner of appearance test

- The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must be at 30±5cm.
- When test the model of transmissive product must add the reflective plate.
- The test direction is base on around 10° of vertical line.
- Temperature: 25±5 °C Humidity: 60±10%RH



• Definition of area:



A: Viewing area B: Outside viewing area

## 10.5.2 Basic principle

- When the standard can not be described, AQL will be applied.
- The sample of the lowest acceptable quality level must be negotiated by both supplier and customer when any dispute happened.

• New item must be added on time when it is necessary.

# **10.6 Inspection Specification**

NO.	Item	Criterion			AQL	
01	Electrical Testing	<ul> <li>1.1 Missing vertical, horizontal segment, segment contrast defect.</li> <li>1.2 Missing character, dot or icon.</li> <li>1.3 Display malfunction.</li> <li>1.4 No function or no display.</li> <li>1.5 Current consumption exceeds product specifications.</li> <li>1.6 LCD viewing angle defect.</li> <li>1.7 Mixed product types.</li> <li>1.8 Flicker</li> </ul>			0.65	
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	Five spots.	White and black or color spots on display ≤ 0.25mm, no more than we spots.  Densely spaced: No more than three spots within 3mm.  Round type: As following drawing			
	LCD and Touch Panel black spots, white spots, contaminati on (non – display) $\Phi = (X+Y)/2$ * Densely spaced: No most and the spots of the spots o	$\Phi = (X+Y)/2$ $X \leftarrow \frac{1}{4}$ $Y$		Size(mm) $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi \le 0.30$ $0.30 < \Phi$	Acceptable Q'ty Accept no dense  2  2  1  0  o spots within 3mm.	2.5
03		Length( mm)  L≦3.0 L≦2.5	mg) Width(mm) $W \le 0.02$ $0.02 < W \le 0.05$ $0.03 < W \le 0.08$ $0.08 < W$	Acceptable Q'ty  Accept no dense  2  Rejection  ro lines within 3mm.	2.5	

NO.	Item	Criterion			AQL	
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction	0.20	ze $\Phi(mm)$ $\Phi \le 0.20$ $0 < \Phi \le 0.50$	Acceptable Q'ty Accept no dense 3	2.5
		specify direction	0.50	$0 < \Phi \le 1.00$ $1.00 < \Phi$	0	-
			Т	otal Q'ty	3	-
05	Scratches	Follow NO.3 -2 Line T	Type.			
06	Chipped glass	x: Chip length y: Ch k: Seal width t: Gla L: Electrode pad length 6.1 General glass chip: 6.1.1 Chip on panel sur z: Chip thickness y Z ≤ 1/2t  1/2t < z ≤ 2t  O Unit: mm O If there are 2 or mor 6.1.2 Corner crack:	Follow NO.3 -2 Line Type.  Symbols:     x: Chip length    y: Chip width    z: Chip thickness    k: Seal width    t: Glass thickness    a: LCD side length    L: Electrode pad length    6.1 General glass chip:     6.1.1 Chip on panel surface and crack between panels:		chip	2.5

NO.	Item	Criterion	AQL
08	Cracked glass	The LCD with extensive crack is not acceptable.	
09	Backlight elements	2.1 Illumination source flickers when lit. 2.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 2.3 Backlight doesn't light or color is wrong.	
10	Bezel	ezel must comply with product specifications.	
11	PCB、COB	<ul> <li>11.1 COB seal may not have pinholes larger than 0.2mm or contamination.</li> <li>11.2 COB seal surface may not have pinholes through to the IC.</li> <li>11.3 The height of the COB should not exceed the height indicated in the assembly diagram.</li> <li>11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places.</li> <li>11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts.</li> <li>11.6 The jumper on the PCB should conform to the product characteristic chart.</li> </ul>	2.5 2.5 2.5 2.5 0.65
12	FPC	12.1 FPC terminal damage $\leq$ 1/2 FPC terminal width and can not affect the function, we judge accept. 12.2 FPC alignment hole damage $\leq$ 1/2 alignment area and can not affect the function, we judge accept.	
13	Soldering	<ul><li>13.1 No cold solder joints, missing solder connections, oxidation or icicle.</li><li>13.2 No short circuits in components on PCB or FPC.</li></ul>	2.5 0.65

NO.	Item	<b>Criterion</b> A			
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad:			
		y: Chip width x: Chip length z: Chip thickness	L 2.5		
		$y \le 0.5 \text{mm} \qquad x \le 1/8 \text{a} \qquad 0 < z \le t$			
07	Glass crack	Non-conductive portion:	2.5		
		y: Chip width x: Chip length z: Chip thickness			
		$y \le L \qquad \qquad x \le 1/8a \qquad \qquad 0 < z \le t$			
		<ul> <li>If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.</li> <li>If the product will be heat sealed by the customer, the alignment mark must mot be damaged.</li> <li>7.2.3 Substrate protuberance and internal crack</li> </ul>			
	y: width x: length				
		$y \le 1/3L \qquad X \le a$			

NO.	Item		Criterion		AQL
14	Touch Panel Chipped glass	k: Seal width t: 'L' L: Electrode pad leng 14.1 General glass cl 14.1.1 Chip on panel  z: Chip thickness  Z≦t  O Unit: mm	gth	x: Chip length  x≤1/8a	2.5
		z: Chip thickness	y: Chip width	x: Chip length	
		z≦t	≤ 1/2 k and not over viewing area	x ≤ 1/8a	
		<ul><li>⊙ Unit: mm</li><li>⊙ If there are 2 or m</li></ul>	nore chips, x is the total	length of each chip	

NO.	Item	Criterion		
15	Touch Panel(Fish eye dent and bubble on film)	$\begin{array}{ c c c }\hline SIZE(mm) & Acceptable Q'ty\\ \hline \Phi \leq 0.2 & Accept no dense\\ \hline 0.2 < D \leq 0.4 & 5\\ \hline 0.4 < D \leq 0.5 & 2\\ \hline 0.5 < D & 0\\ \hline \end{array}$	2.5	
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion ( $\leq 2.5\%$ ), it is acceptable.		
17	Touch Panel Linearity	Less than 2.5% is acceptable.		
18	LCD Ripple	Touch the touch panel, can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g		
19	General appearance	<ul> <li>19.1 Pin type must match type in specification sheet.</li> <li>19.2 LCD pin loose or missing pins.</li> <li>19.3 Product packaging must the same as specified on packaging specification sheet.</li> <li>19.4 Product dimension and structure must conform to product specification sheet.</li> </ul>		

## 11. Handling Precaution

### 11.1 Handling of LCM

- Avoid external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance, do not lick or swallow. When the liquid is attaching to your hand, skin, cloth, etc., wash it thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should wear protections whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface, be careful when peeling off this protective film since static electricity may be generated.

#### 11.2 Storage

- Store it in an ambient temperature of 25±10°C, and in a relative humidity of 50±10%RH. Don't expose to sunlight or fluorescent light.
- Store it in a clean environment, free from dust, active gas, and solvent.
- Store it in anti-static electricity container.
- Store it without any physical load.

### 11.3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: no higher than 280±10°C and less than 3 sec during hand soldering.

• Rewiring: no more than 2 times.

# 12. Packing Method

No.	Item	Dimensions(mm)	Quantity	Remark
1	LCM Module	50.00*69.20*2.45	270PCS	
2	TRAY	388*347*20 (include 15pcs products/one tray)	9PCS	
3	SMALL CARTON	393*345*115 (include 135pcs products/one carton)	2PCS	_
4	LARGE CARTON	430*380*270 (include 270pcs products/one carton)	1PCS	-